



Material Content Data Sheet



Sales Product Name				BSZ097N04LS G		Issued		3. October 2018	
MA#				MA001831304					
Package				PG-TSDSON-8-1		Weight*		36.12 mg	
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	0.804	2.23	2.23	22256	22256	
leadframe	inorganic material	phosphorus	7723-14-0	0.002	0.01		66		
	non noble metal	zinc	7440-66-6	0.009	0.03		262		
	non noble metal	iron	7439-89-6	0.189	0.52		5242		
wire	non noble metal	copper	7440-50-8	7.689	21.29	21.85	212865	218435	
	non noble metal	copper	7440-50-8	0.037	0.10	0.10	1017	1017	
	encapsulation	organic material	carbon black	1333-86-4	0.037	0.10		1033	
	plastics	epoxy resin	-	1.921	5.32		53177		
	inorganic material	silicondioxide	60676-86-0	16.690	46.21	51.63	462068	516278	
leadfinish	non noble metal	tin	7440-31-5	0.370	1.02	1.02	10245	10245	
plating	noble metal	silver	7440-22-4	0.081	0.22	0.22	2237	2237	
solder	non noble metal	tin	7440-31-5	0.022	0.06		615		
	noble metal	silver	7440-22-4	0.028	0.08		768		
	non noble metal	lead	7439-92-1	1.060	2.94	3.08	29350	30733	
heatspreader	inorganic material	phosphorus	7723-14-0	0.001	0.00		33		
	non noble metal	zinc	7440-66-6	0.005	0.01		130		
	non noble metal	iron	7439-89-6	0.094	0.26		2602		
heat sink CLIP	non noble metal	copper	7440-50-8	3.816	10.56	10.83	105643	108408	
	inorganic material	phosphorus	7723-14-0	0.001	0.00		27		
	non noble metal	zinc	7440-66-6	0.004	0.01		108		
	non noble metal	iron	7439-89-6	0.078	0.22		2169		
	non noble metal	copper	7440-50-8	3.182	8.81	9.04	88087	90391	
*deviation	< 10%		Sum in total:			100.00		1000000	

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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